

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-9 (Canceled).

Claim 10 (Currently Amended): A method for manufacturing an electronic part in which a layer having a uniform thickness is formed, the method comprising:

forming ~~[[a]]~~ at least one conductor portion on a surface of a first support member;

forming an insulating sheet on a second support member;

bringing ~~[[an]]~~ said insulating sheet into contact with the at least one conductor portion from above; and

pressing the second support member with the insulating sheet to a height of the at least one conductor portion using the at least one conductor portion as a stopper to make the height of the insulating sheet equal to the height of the at least one conductor portion.

Claim 11 (Currently Amended): A method for manufacturing an electronic part according to claim 10, wherein said at least one conductor portion and said insulating sheet are detached from said surface, after making the height of said insulating sheet equal to the height of said at least one conductor portion.

Claim 12 (Currently Amended): A method for manufacturing an electronic part according to claim 10, wherein said first support member is a substrate of said electronic part.

Claim 13 (Previously Presented): A method for manufacturing an electronic part according to claim 11, wherein a B-stage sheet is used as said insulating sheet.

Claim 14 (Previously Presented): A method for manufacturing an electronic part according to claim 12, wherein a B-stage sheet is used as said insulating sheet.

Claim 15 (Previously Presented): A method for manufacturing an electronic part according to claim 11, wherein a thermoplastic insulating sheet is used as said insulating sheet.

Claim 16 (Previously Presented): A method for manufacturing an electronic part according to claim 12, wherein a thermoplastic insulating sheet is used as said insulating sheet.

Claim 17 (Previously Presented): A method for manufacturing an electronic part according to claim 11, wherein heating is performed in addition to said pressing.

Claim 18 (Previously Presented): A method for manufacturing an electronic part according to claim 12, wherein heating is performed in addition to said pressing.

Claim 19 (Previously Presented): A method for manufacturing an electronic part according to claim 13, wherein heating is performed in addition to said pressing.

Claim 20 (Previously Presented): A method for manufacturing an electronic part according to claim 14, wherein heating is performed in addition to said pressing.

Claim 21 (Previously Presented): A method for manufacturing an electronic part according to claim 15, wherein heating is performed in addition to said pressing.

Claim 22 (Previously Presented): A method for manufacturing an electronic part according to claim 16, wherein heating is performed in addition to said pressing.

Claim 23 (Currently Amended): A method for manufacturing an electronic part in which a layer having a uniform thickness is formed, the method comprising:

forming a power supply film on a surface of a first support member;

forming ~~[[a]]~~ at least one conductor portion by plating using the power supply film as an electrode;

forming an insulating sheet on a second support member;

bringing ~~[[an]]~~ said insulating sheet into contact with the at least one conductor portion from above;

pressing the second support member including the insulating sheet to the height of the at least one conductor portion using said at least one conductor portion; and
removing said power supply film.

Claim 24 (Currently Amended): A method for manufacturing an electronic part according to claim 23, wherein said at least one conductor portion and said insulating sheet are detached from said surface, after making the height of said insulating sheet equal to the height of said at least one conductor portion.

Claim 25 (Currently Amended): A method of manufacturing an electronic part according to claim 23, wherein said first support member is a substrate of said electronic part.

Claim 26 (Previously Presented): A method for manufacturing an electronic part according to claim 24, wherein a B-stage sheet is used as said insulating sheet.

Claim 27 (Previously Presented): A method for manufacturing an electronic part according to claim 25, wherein a B-stage sheet is used as said insulating sheet.

Claim 28 (Previously Presented): A method for manufacturing an electronic part according to claim 24, wherein a thermoplastic insulating sheet is used as said insulating sheet.

Claim 29 (Previously Presented): A method for manufacturing an electronic part according to claim 25, wherein a thermoplastic insulating sheet is used as said insulating sheet.

Claim 30 (Previously Presented): A method for manufacturing an electronic part according to claim 24, wherein heating is performed in addition to said pressing.

Claim 31 (Previously Presented): A method for manufacturing an electronic part according to claim 25, wherein heating is performed in addition to said pressing.

Claim 32 (Previously Presented): A method for manufacturing an electronic part according to claim 26, wherein heating is performed in addition to said pressing.

Claim 33 (Previously Presented): A method for manufacturing an electronic part according to claim 27, wherein heating is performed in addition to said pressing.

Claim 34 (Previously Presented): A method for manufacturing an electronic part according to claim 28, wherein heating is performed in addition to said pressing.

Claim 35 (Previously Presented): A method for manufacturing an electronic part according to claim 29, wherein heating is performed in addition to said pressing.